

AMENDMENTS TO THE SPECIFICATION

Add text before "FIELD OF THE INVENTION: on page 1:

This is a divisional application based upon U.S. patent application number 09/941,761, filed on August 30, 2001, which is hereby incorporated in its entirety by reference.

Application No.: NOT YET ASSIGNED

Docket No.: M4065.0468/P468-B

Replace the title with the following:

METHOD ~~AND STRUCTURE~~ FOR TEMPORARILY ISOLATING A DIE
FROM A COMMON CONDUCTOR TO FACILITATE WAFER LEVEL TESTING

Please amend paragraph 7 beginning on page 3 with the following:

The present invention provides a method ~~and apparatus~~ which facilitates temporary isolation of a die from one or more common conductors during wafer level testing. The one or more common conductors extend over a wafer and are connected to a plurality of dice on the wafers which are undergoing testing. A temporary isolation device (e.g., a diode, transistor or other element) is interposed between each die and the common conductor. The temporary isolation device can be used to isolate a die from the common conductor during wafer level testing whenever such isolation is needed.

Please amend the abstract as follows:

The invention provides a method ~~and apparatus~~ for temporarily isolating a die from other dice on a wafer commonly connected to one or more common conductors. The conductors are connected to each die through a temporary isolation device, such as a diode. The common conductor supplies a signal to all dice during one set of test procedures, while the temporary isolation device can be used to isolate a die from the common conductor during another set of test procedures.